

PMWD15UN

Dual μ TrenchMOS™ ultra low level FET

Rev. 01 — 4 February 2003

Product data

1. Product profile

1.1 Description

Dual common drain N-channel enhancement mode field-effect transistor in a plastic package using TrenchMOS™ technology.

Product availability:

PMWD15UN in SOT530-1 (TSSOP8).

1.2 Features

- Surface mounting package
- Very low threshold
- Low profile
- Fast switching.

1.3 Applications

- Portable appliances
- Battery Management
- PCMCIA cards
- Load switching.

1.4 Quick reference data

- $V_{DS} \leq 20 \text{ V}$
- $P_{tot} \leq 2.3 \text{ W}$
- $I_D \leq 5 \text{ A}$
- $R_{DS(on)} \leq 18.5 \text{ m}\Omega$.

2. Pinning information

Table 1: Pinning - SOT530-1 (TSSOP8), simplified outline and symbol

Pin	Description	Simplified outline	Symbol
1,8	drain (d)	Top view MBK885	mbi600
2,3	source1 (s1)		
4	gate1 (g1)		
5	gate2 (g2)		
6,7	source2 (s2)		
		SOT530-1 (TSSOP8)	



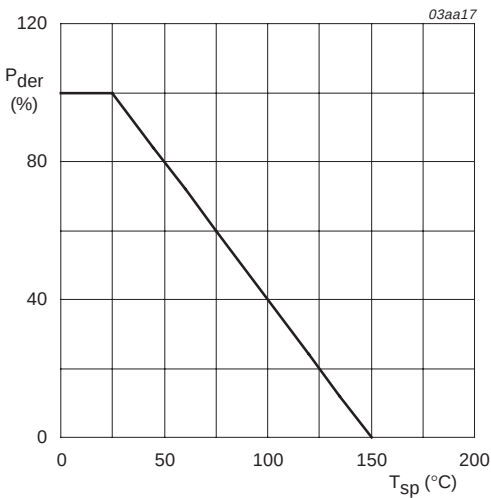
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3. Limiting values

Table 2: Limiting values

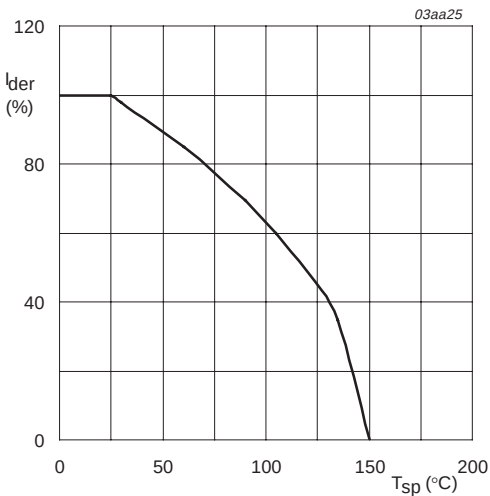
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage (DC)	$25\text{ °C} \leq T_j \leq 150\text{ °C}$	-	20	V
V_{DGR}	drain-gate voltage (DC)	$25\text{ °C} \leq T_j \leq 150\text{ °C}$; $R_{GS} = 20\text{ k}\Omega$	-	20	V
V_{GS}	gate-source voltage		-	± 12	V
I_D	drain current (DC)	$T_{sp} = 25\text{ °C}$; $V_{GS} = 4.5\text{ V}$; Figure 2 and 3	-	5	A
		$T_{sp} = 100\text{ °C}$; $V_{GS} = 4.5\text{ V}$; Figure 2	-	3	A
I_{DM}	peak drain current	$T_{sp} = 25\text{ °C}$; pulsed; $t_p \leq 10\text{ }\mu\text{s}$; Figure 3	-	18	A
P_{tot}	total power dissipation	$T_{sp} = 25\text{ °C}$; Figure 1	-	2.3	W
T_{stg}	storage temperature		-55	+150	°C
T_j	junction temperature		-55	+150	°C
Source-drain diode					
I_S	source (diode forward) current (DC)	$T_{sp} = 25\text{ °C}$	-	2	A
I_{SM}	peak source (diode forward) current	$T_{sp} = 25\text{ °C}$; pulsed; $t_p \leq 10\text{ }\mu\text{s}$	-	7	A



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

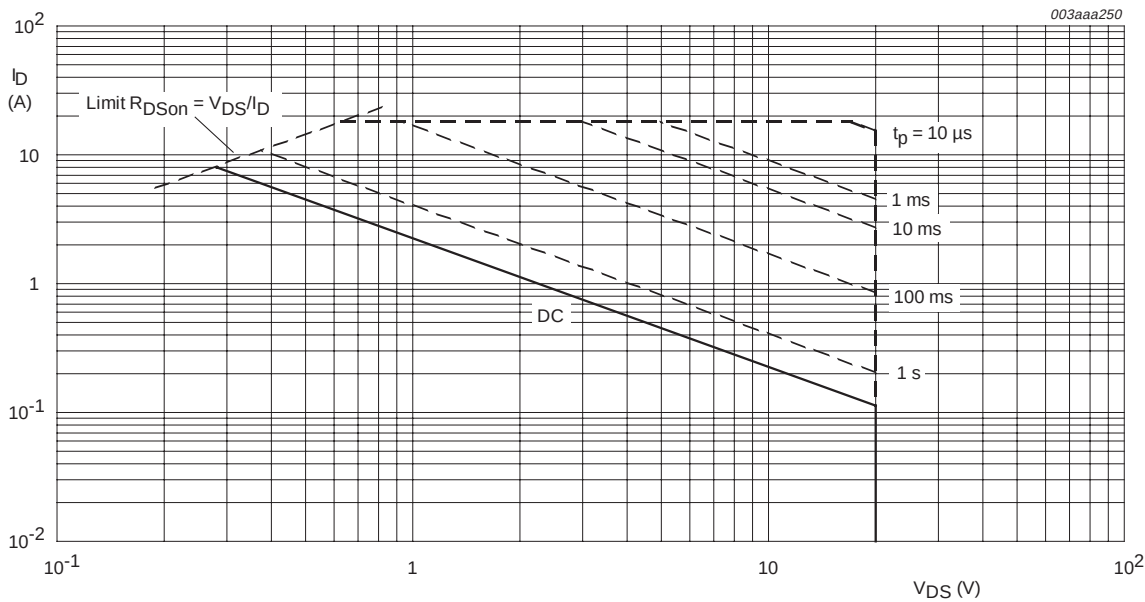
Fig 1. Normalized total power dissipation as a function of solder point temperature.



$V_{GS} \geq 4.5 \text{ V}$

$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized continuous drain current as a function of solder point temperature.



$T_{sp} = 25^{\circ}C$; I_{DM} is single pulse

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage.

4. Thermal characteristics

Table 3: Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point.	Figure 4	-	55	70	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient.	minimum footprint; mounted on printed circuit board	-	100	-	K/W

4.1 Transient thermal impedance

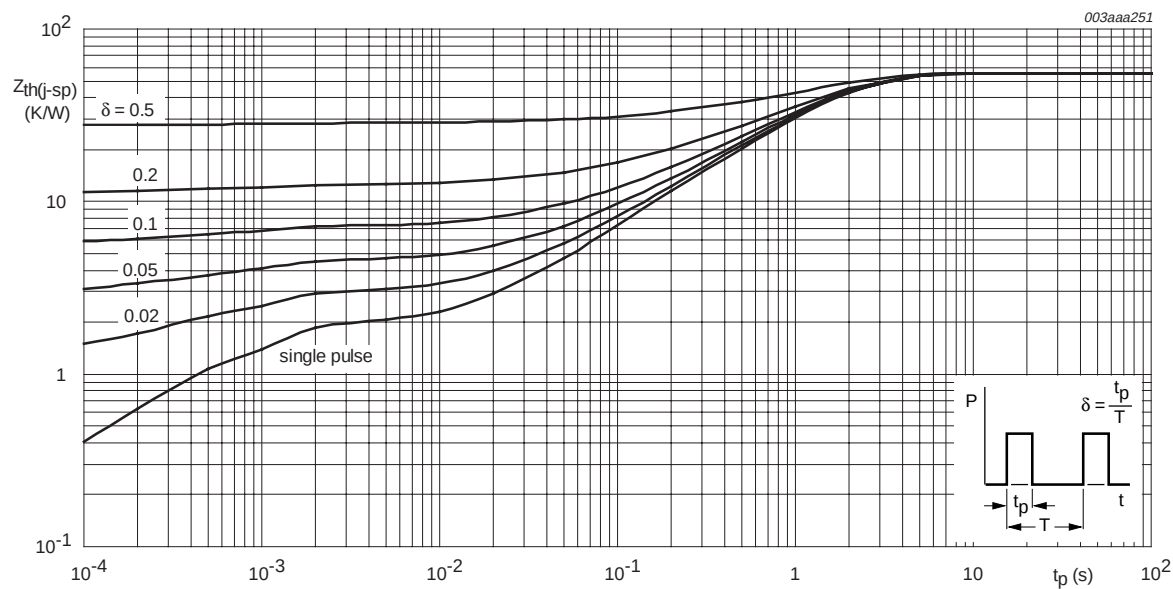


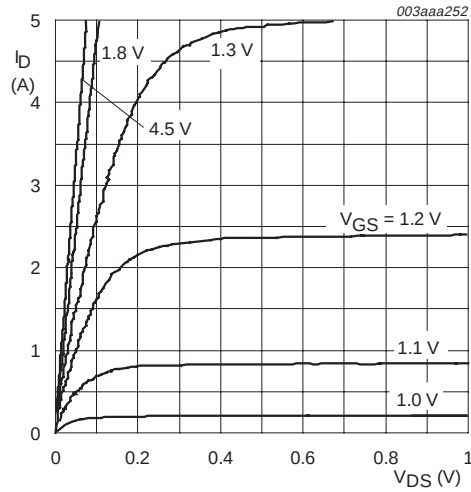
Fig 4. Transient thermal impedance from junction to solder point as a function of pulse duration.

5. Characteristics

Table 4: Characteristics

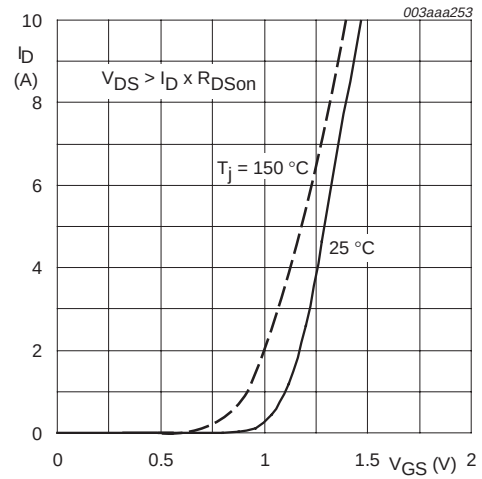
$T_j = 25\text{ }^\circ\text{C}$ unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250\text{ }\mu\text{A}$; $V_{GS} = 0\text{ V}$				
		$T_j = 25\text{ }^\circ\text{C}$	20	-	-	V
		$T_j = -55\text{ }^\circ\text{C}$	18	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1\text{ mA}$; $V_{DS} = V_{GS}$; Figure 9	0.45	0.7	-	V
I_{DSS}	drain-source leakage current	$V_{DS} = 20\text{ V}$; $V_{GS} = 0\text{ V}$				
		$T_j = 25\text{ }^\circ\text{C}$	-	-	1	μA
		$T_j = 150\text{ }^\circ\text{C}$	-	-	100	μA
I_{GSS}	gate-source leakage current	$V_{GS} = \pm 10\text{ V}$; $V_{DS} = 0\text{ V}$	-	-	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 4.5\text{ V}$; $I_D = 5\text{ A}$; Figure 7 and 8				
		$T_j = 25\text{ }^\circ\text{C}$	-	15.3	18.5	m Ω
		$T_j = 150\text{ }^\circ\text{C}$	-	26	31	m Ω
		$V_{GS} = 1.8\text{ V}$; $I_D = 4.5\text{ A}$; Figure 7	-	20	28.5	m Ω
		$V_{GS} = 2.5\text{ V}$; $I_D = 5\text{ A}$; Figure 7	-	17	20.5	m Ω
Dynamic characteristics						
$Q_{g(tot)}$	total gate charge	$I_D = 4\text{ A}$; $V_{DD} = 16\text{ V}$; $V_{GS} = 4.5\text{ V}$; Figure 13	-	22.2	-	nC
Q_{gs}	gate-source charge		-	2.1	-	nC
Q_{gd}	gate-drain (Miller) charge		-	6.2	-	nC
C_{iss}	input capacitance	$V_{GS} = 0\text{ V}$; $V_{DS} = 16\text{ V}$; $f = 1\text{ MHz}$; Figure 11	-	1454	-	pF
C_{oss}	output capacitance		-	282	-	pF
C_{rss}	reverse transfer capacitance		-	188	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DD} = 10\text{ V}$; $I_D = 1\text{ A}$; $V_{GS} = 4.5\text{ V}$; $R_G = 6\text{ }\Omega$	-	14.7	-	ns
t_r	rise time		-	22.4	-	ns
$t_{d(off)}$	turn-off delay time		-	57	-	ns
t_f	fall time		-	33	-	ns
Source-drain diode						
V_{SD}	source-drain (diode forward) voltage	$I_S = 5\text{ A}$; $V_{GS} = 0\text{ V}$; Figure 12	-	0.67	1.2	V
t_{rr}	reverse recovery time	$I_S = 5\text{ A}$; $di_S/dt = -100\text{ A}/\mu\text{s}$; $V_R = 20\text{ V}$;	-	45	-	ns
Q_r	recovered charge	$V_{GS} = 0\text{ V}$	-	12.3	-	nC



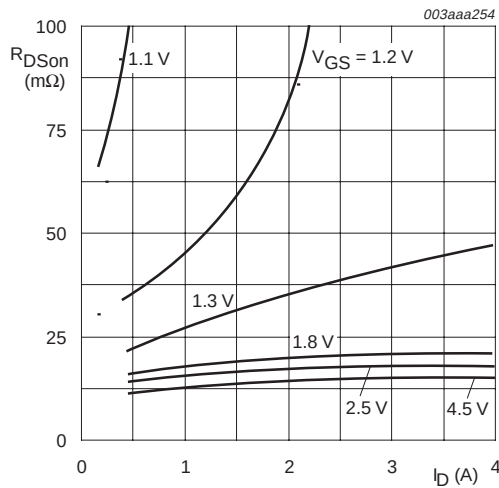
$T_j = 25^\circ\text{C}$

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values.



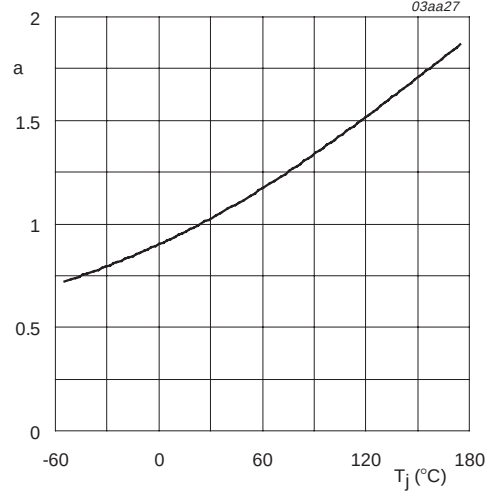
$T_j = 25^\circ\text{C}$ and 150°C ; $V_{DS} > I_D \times R_{DSon}$

Fig 6. Transfer characteristics: drain current as a function of gate-source voltage; typical values.



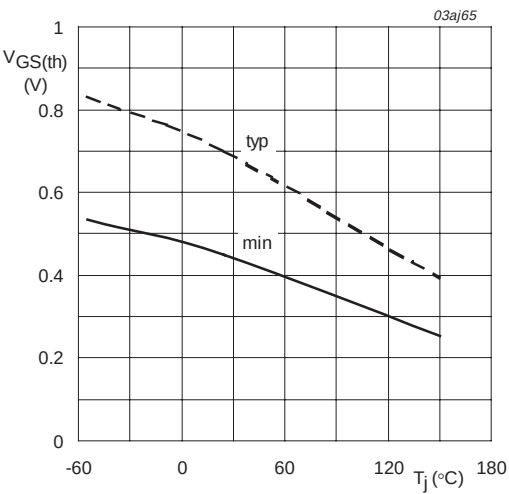
$T_j = 25^\circ\text{C}$

Fig 7. Drain-source on-state resistance as a function of drain current; typical values.



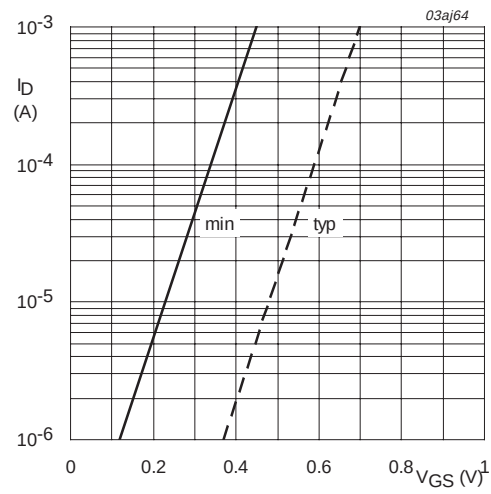
$$a = \frac{R_{DSon}}{R_{DSon(25^\circ\text{C})}}$$

Fig 8. Normalized drain source on-state resistance factor as a function of junction temperature.



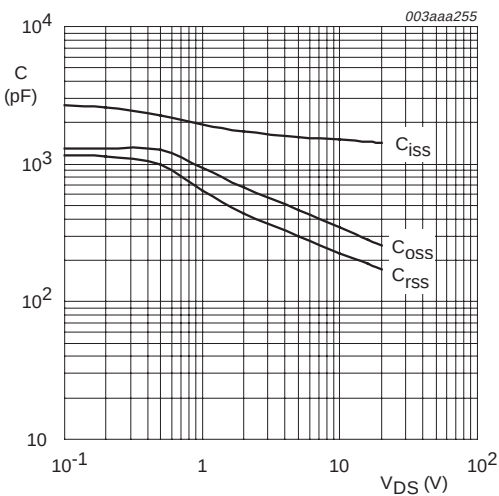
$I_D = 1 \text{ mA}$; $V_{DS} = V_{GS}$

Fig 9. Gate-source threshold voltage as a function of junction temperature.



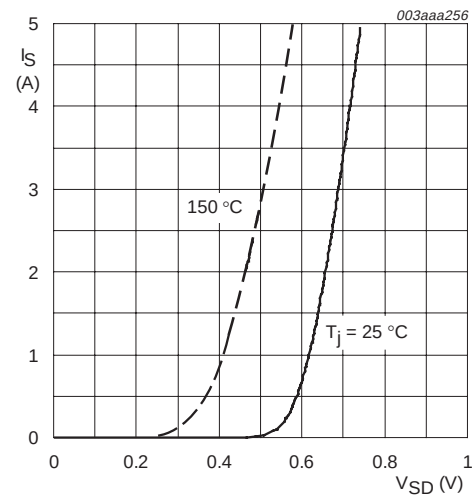
$T_J = 25 \text{ }^\circ\text{C}$; $V_{DS} = 5 \text{ V}$

Fig 10. Sub-threshold drain current as a function of gate-source voltage.



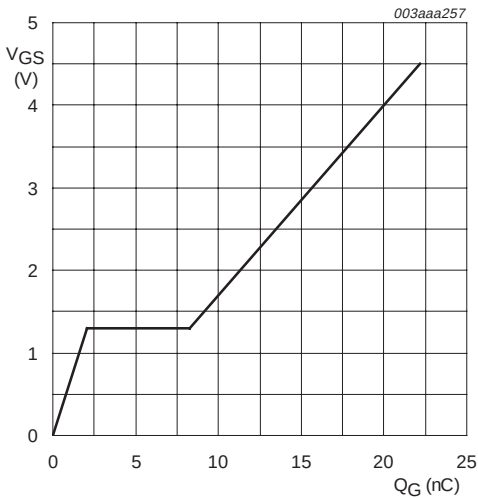
$V_{GS} = 0 \text{ V}$; $f = 1 \text{ MHz}$

Fig 11. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values.



$T_J = 25 \text{ }^\circ\text{C}$ and $150 \text{ }^\circ\text{C}$; $V_{GS} = 0 \text{ V}$

Fig 12. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values.



$I_D = 4\text{ A}; V_{DD} = 16\text{ V}$

Fig 13. Gate-source voltage as a function of gate charge; typical values.

6. Package outline

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 4.4 mm

SOT530-1

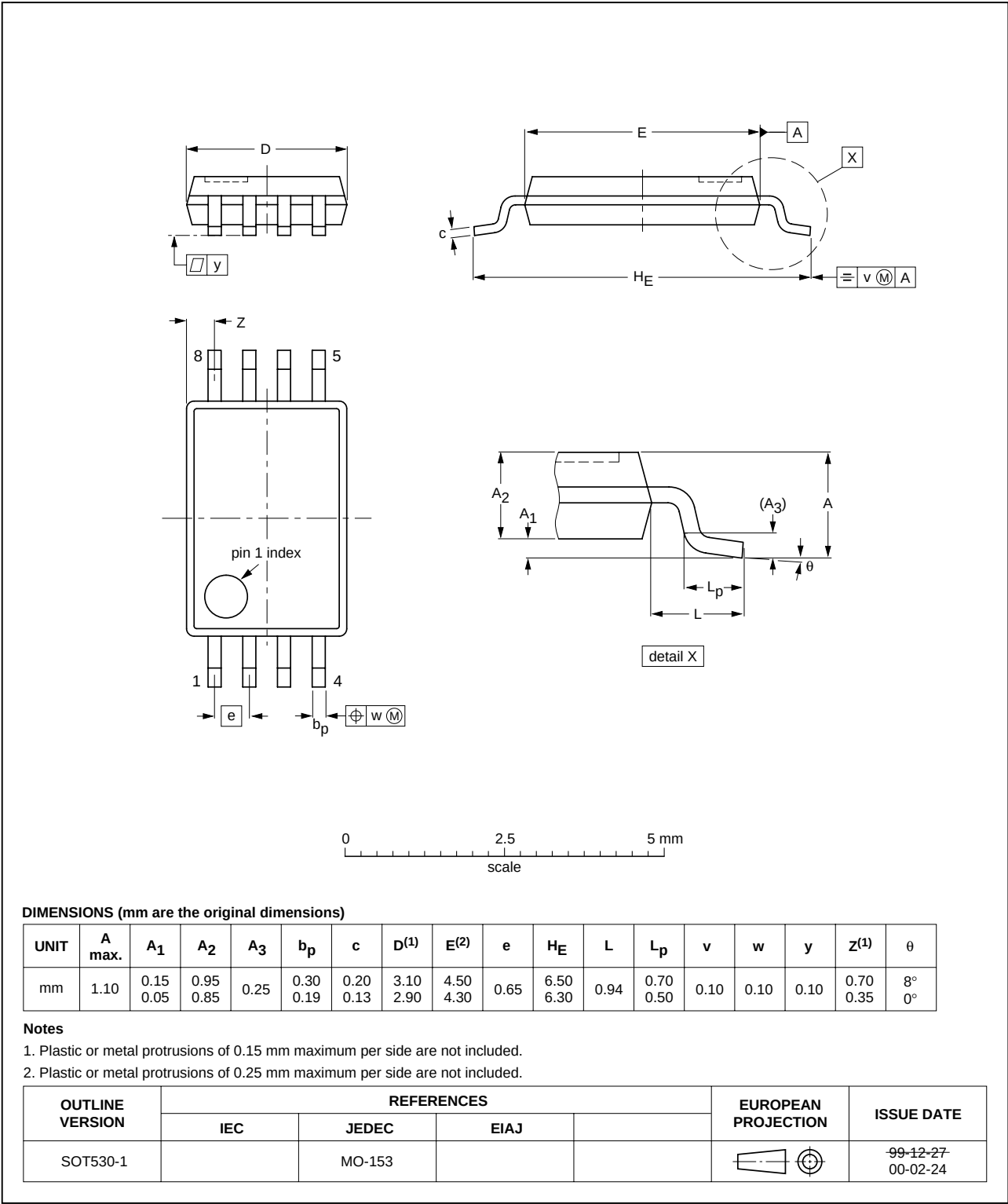


Fig 14. SOT530-1 (TSSOP8).

7. Revision history

Table 5: Revision history

Rev	Date	CPCN	Description
01	20030204	-	Product data; (9397 750 10829)

8. Data sheet status

Level	Data sheet status ^[1]	Product status ^{[2][3]}	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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